

HSF

NOTES:

Rated Current:5.0AMP.(20°C,3*2P-3*15P)
 3.0AMP.(20°C,3*16P-3*40P) △A5

Contact Resistance:20mΩ Max.

Withstand Voltage:1000V AC/DC

Insulation Resistance:1000MΩ Min.

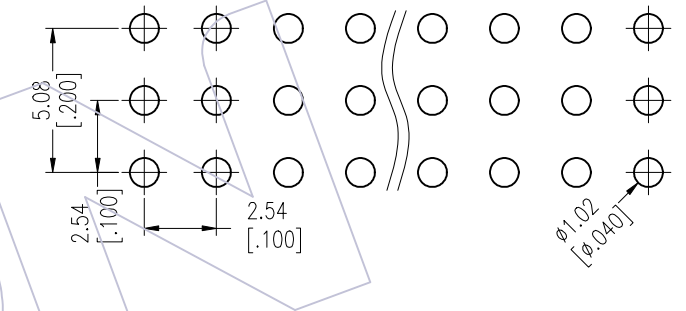
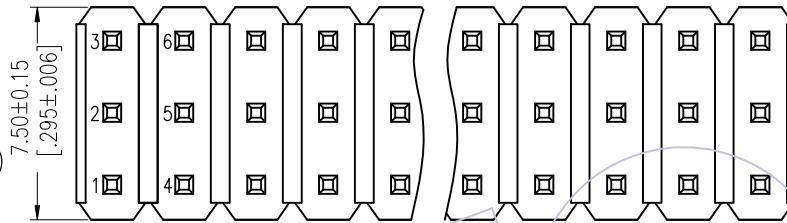
Operation Temperature:-40°C to +125°C(Gold Plating)
 -40°C to +105°C(Tin Plating)

Contact Material:Copper Alloy

Contact Plating:Au or Sn Over 30u" Min Ni △A5

Insulator Material:PA9T+G.F UL94V-0 BK

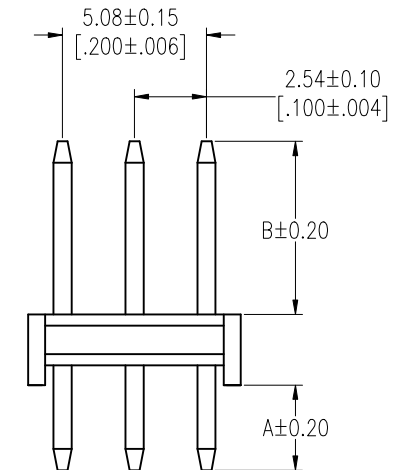
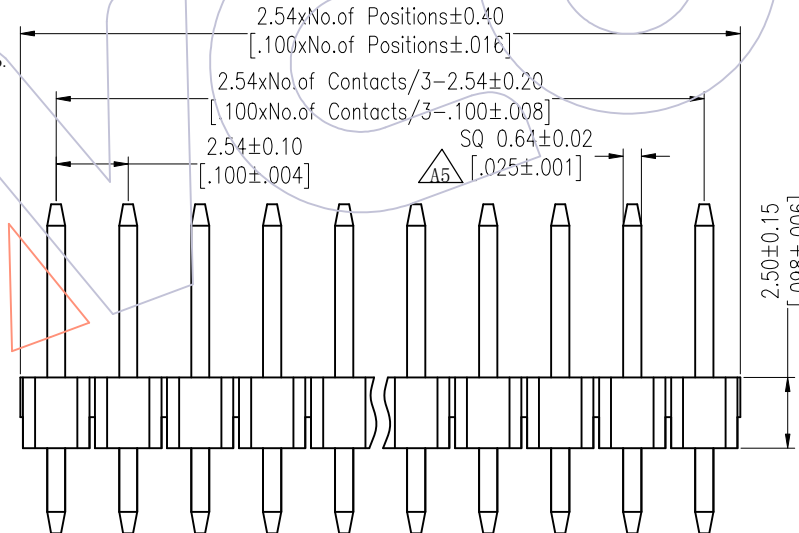
Recommended P.C.B Layout (Top Side)
 (PCB BOARD TOLERANCE±0.05)
 (PCB Thickness:T=1.60m)



1125-1 3 XX XX S XXX C X XX

Plastic Layer
 Plastic Row
 No.of Pins
 Per Row:02-40
 Contact Plating
 G0=Gold Flash
 G3=10u"Au, BG3=8u"PdNi+2u"Au
 G4=15u"Au, BG4=13u"PdNi+2u"Au
 G5=30u"Au, BG5=28u"PdNi+2u"Au
 S0=Gold Flash/Tin
 S3=10u"Au/Sn, P3=8u"PdNi+2u"Au/Sn
 S4=15u"Au/Sn, P4=13u"PdNi+2u"Au/Sn
 S5=30u"Au/Sn, P5=28u"PdNi+2u"Au/Sn
 SN=Bright Tin
 SM=Matte Tin

Series No.
 01-99
 Packing
 0=PE Bag
 Insulator Material
 C=PA9T(Standard)
 Pin Length
 L(See Table)
 Type:
 S:S/T



Item	Pin Length	A	B	Mating
Standard	9.0	3.0	3.5	2135/2150T/2157
	9.5		4.0	2145/2150
	10.5		5.0	2168T/2171T
	11.3		5.84	2171/2185X
Standard	8.0	2.0 (THR)	3.5	2135/2150T/2157
	8.5		4.0	2145/2150
	9.5		5.0	2168T/2171T
	10.3		5.84	2171/2185X
Alternate				

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
A5	2025/05/30	Standardization Drawing	CP	OPERATION	DRAW	2025/05/30	SCALE	Fit	1125-13XXXXXXC0XX
A4	2018/01/22	Modify P/N	Ruipeng	x.X ±0.40	CP	2025/05/30	UNIT	mm [inch]	TITLE:
A3	2016/02/19	MODIFY DRAWING	William Chen	x.xx ±0.25	CHECK	2025/05/30	SIZE	A4	PH2.54 THREE ROW S/T H=2.5
A0	2012/06/16	NEW	William Chen	x.xxx ±0.15	TANG	2025/05/30	SHEET	1/2	Customer NO.
				Angle ± 3'	APPROVE	2025/05/30	PROJ.		
				DIM TOL	Steven Zhao				

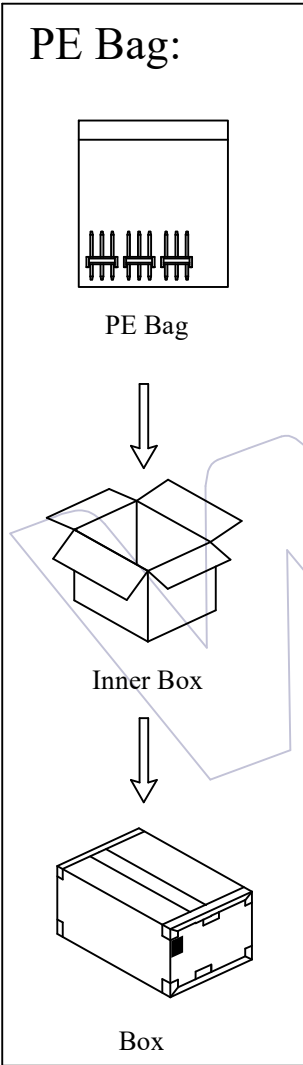


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HSF

Packing:



Packaging Quantity Refers To The Following Table

PINS /Row	Q' ty/Bag (10.0 ≤ L ≤ 16.0)	PINS /Row	Q' ty/Bag (10.0 ≤ L ≤ 16.0)
2	1,000	22	150
3	1,000	23	150
4	1,000	24	150
5	500	25	150
6	500	26	100
7	500	27	100
8	500	28	100
9	500	29	100
10	300	30	100
11	300	31	100
12	300	32	100
13	300	33	100
14	300	34	100
15	200	35	50
16	200	36	50
17	200	37	50
18	200	38	50
19	200	39	50
20	200	40	50
21	150		

A5	2025/05/30	Standardization Drawing	CP	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
A4	2018/01/22	Modify P/N	Ruipeng	x.X ±0.40	CP	2025/05/30	UNIT	mm [inch]	1125-13XXXXXXXCOXX
A3	2016/02/19	MODIFY DRAWING	William Chen	x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
A0	2012/06/16	NEW	William Chen	x.xxx ±0.15	TANG	2025/05/30	SHEET	2/2	PH2.54 THREE ROW S/T H=2.5
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle ± 3'	APPROVE	DATE	PROJ.		Customer NO.
				DIM TOL	Steven Zhao	2025/05/30			

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